

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

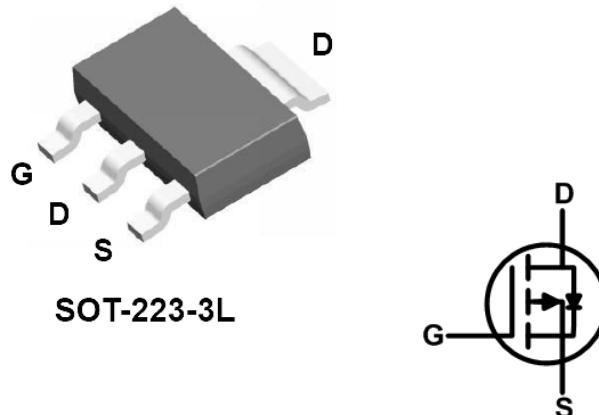
**Product Summary**

BVDSS	RDS(ON)	ID
-100V	194mΩ	-10A

**Description**

The XR10P10K is the high cell density trenched N-ch MOSFETs, which provides excellent RDS(ON) and efficiency for most of the small power switching and load switch applications.

The XR10P10K meet the RoHS and Green Product requirement with full function reliability approved.

**SOT223 Pin Configuration****Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-10	A
$I_D @ T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-4	A
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-2.5	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-2.0	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-20	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	---	mJ
$I_{AS}$	Avalanche Current	---	A
$P_D @ T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	2.4	W
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	1	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	69.4	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	8	°C/W

## P-Ch 100V Fast Switching MOSFETs

P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-100	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_D=-3\text{A}$	---	194	242	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-2\text{A}$	---	217	271	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-1.2	-2	-2.3	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-100\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\text{uA}$
		$V_{\text{DS}}=-100\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=85^\circ\text{C}$	---	---	-30	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	---	---	$\Omega$
$Q_g$	Total Gate Charge (-10V)	$V_{\text{DS}}=-50\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_D=-2\text{A}$	---	29	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	2.9	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	5.2	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-50\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=3.3\Omega$ , $I_D=-2\text{A}$	---	9.6	---	$\text{ns}$
$T_r$	Rise Time		---	17	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	60	---	
$T_f$	Fall Time		---	36	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1290	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	34	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	28	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	10.0	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

## Typical Characteristics

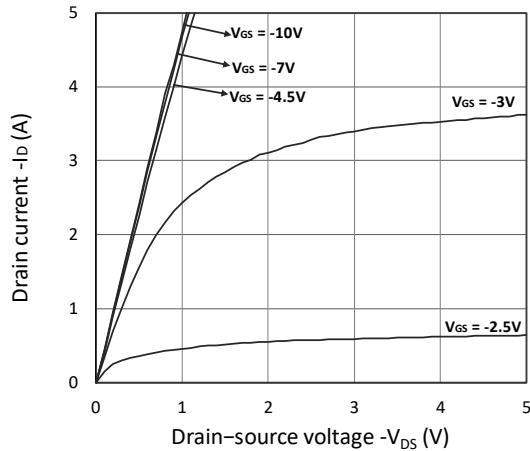


Figure 1. Output Characteristics

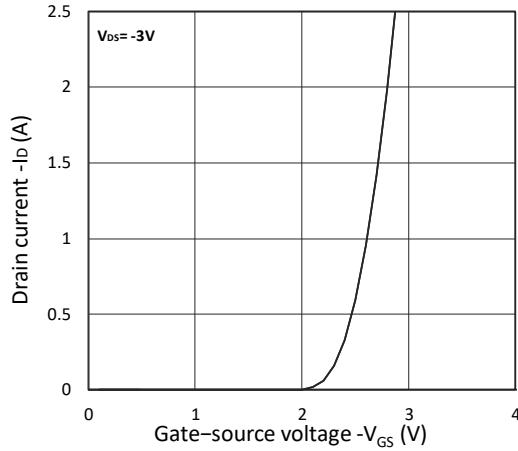


Figure 2. Transfer Characteristics

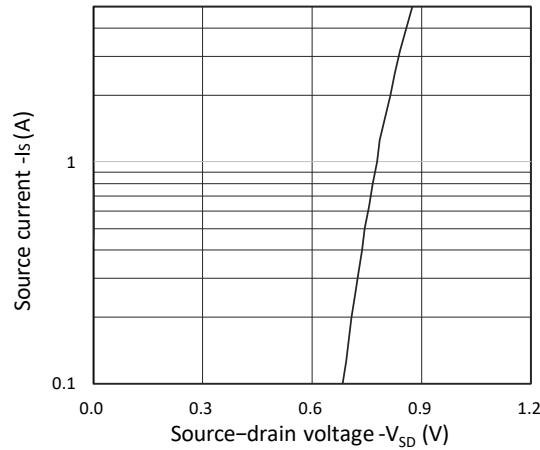
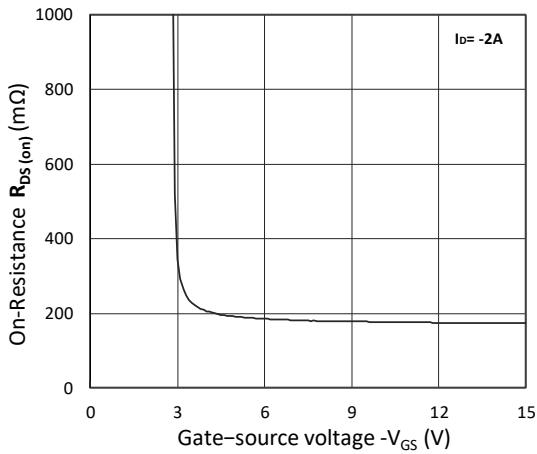
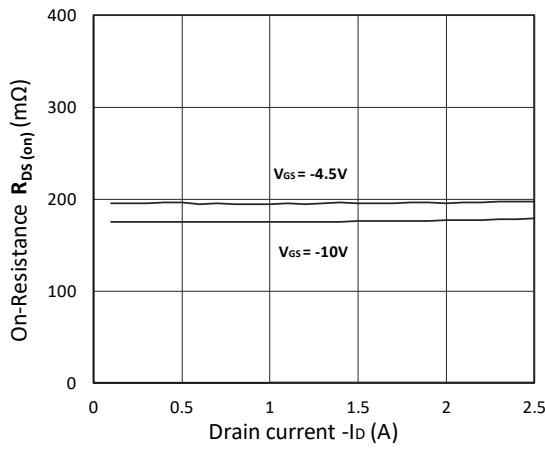
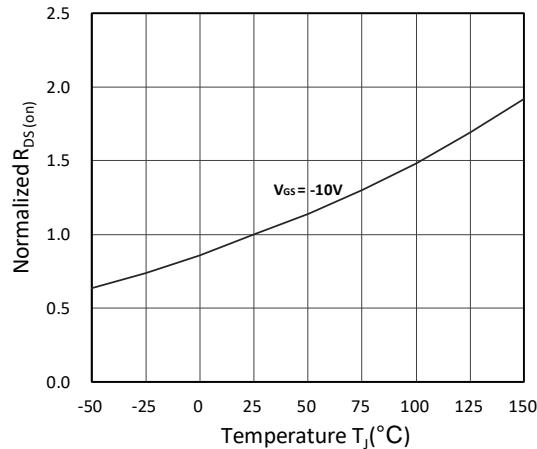


Figure 3. Forward Characteristics of Reverse

Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(ON)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

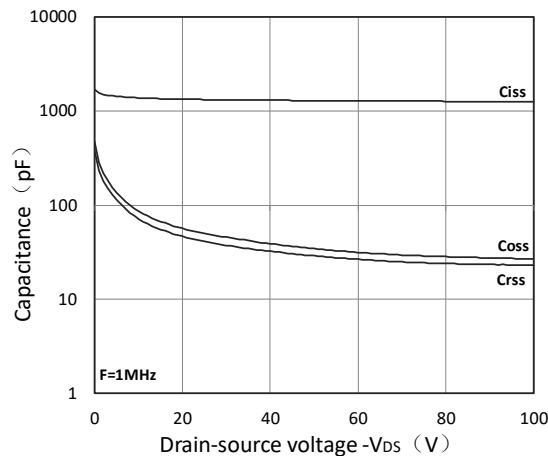


Figure 7. Capacitance Characteristics

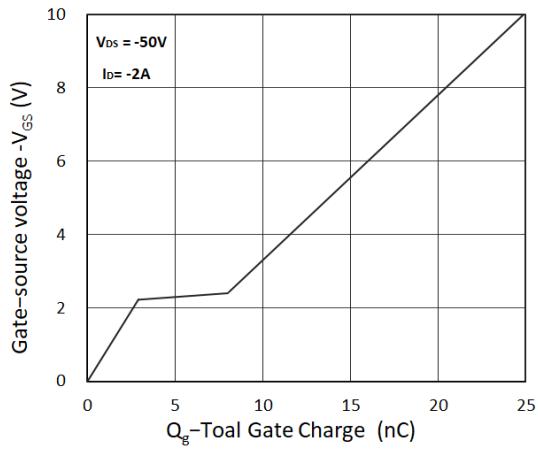
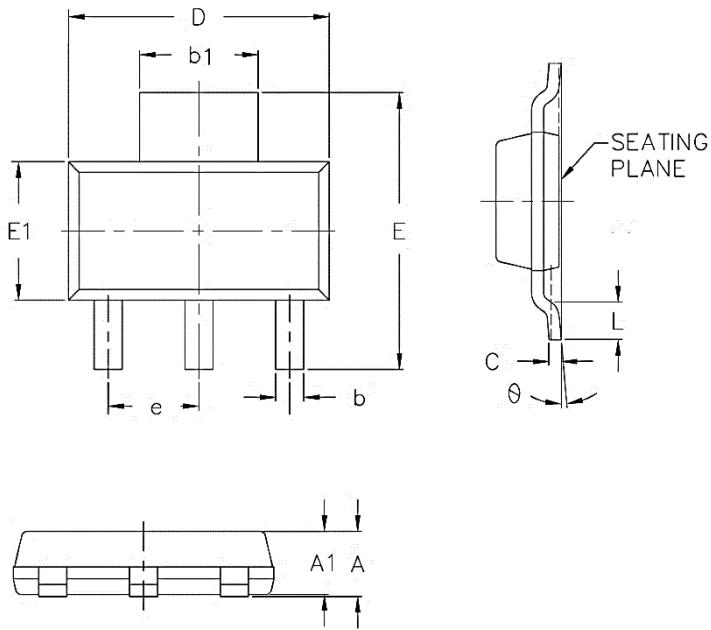


Figure 8. Gate Charge Characteristics

## Mechanical Dimensions for SOT-223-3L

## COMMON DIMENSIONS



SYMBOL	MM	
	MIN	MAX
A	-	1.80
A1	1.45	1.75
b	0.60	0.84
b1	2.90	3.10
C	0.23	0.35
D	6.20	6.70
E	6.70	7.30
E1	3.30	3.70
e	2.30BSC	
L	0.80	-
θ	0°	10°